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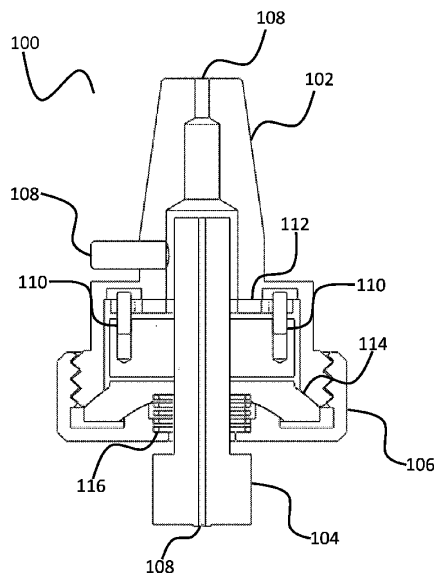


Figure 1

(57) **Abstract:** A die placement system provides a tip body and die placement head to ensure planarity of a die to substrate without the need for calibration prior to each pick and place operation. A self-aligning tip incorporated into a tip body aids in die placement/attachment. This tip provides for global correction of planarity errors that exist between a die and substrate, regardless of whether those errors stem from gantry (i.e. die-side misalignment) or machine deck tool (i.e. substrate-side misalignment) misalignment.



WO 2022/046566 A1